

HSM88AS

Silicon Schottky Barrier Diode for Balanced Mixer

REJ03G0135-0600Z
(Previous: ADE-208-046E)
Rev.6.00
Nov.06.2003

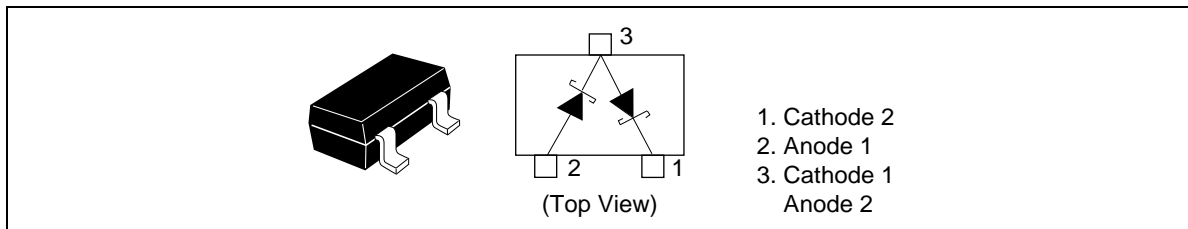
Features

- Proof against high voltage.
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HSM88AS	C1	MPAK

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V _R	10	V
Average rectified current	I _O * ¹	15	mA
Junction temperature	T _j	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Note: 1. Per one device

Electrical Characteristics *¹

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V _{F1}	0.35	—	0.42	V	I _F = 1 mA
	V _{F2}	0.50	—	0.58		I _F = 10 mA
Reverse current	I _{R1}	—	—	0.2	μA	V _R = 2 V
	I _{R2}	—	—	10		V _R = 10 V
Capacitance	C	—	—	0.85	pF	V _R = 0 V, f = 1 MHz
Capacitance deviation	ΔC	—	—	0.10	pF	V _R = 0 V, f = 1 MHz
Forward voltage deviation	ΔV _F	—	—	10	mV	I _F = 10 mA
ESD-Capability * ²	—	30	—	—	V	C = 200 pF, R = 0 Ω, Both forward and reverse direction 1 pulse.

Notes: 1. Per one device

2. Failure criterion ; I_R ≥ 0.4 μA at V_R = 2 V

Main Characteristics

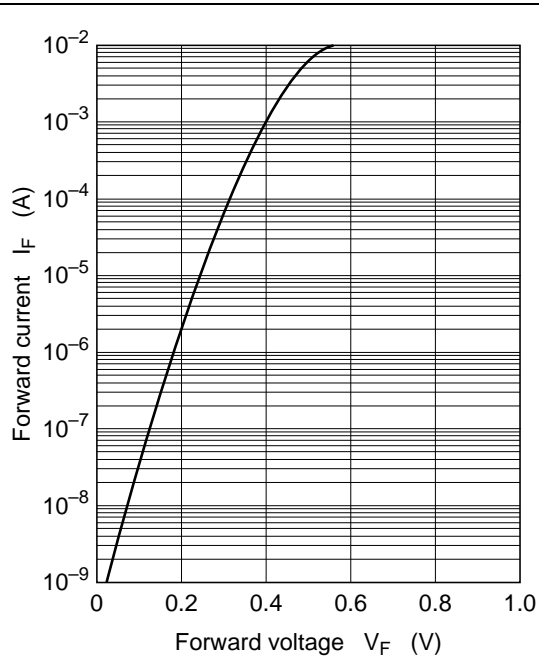


Fig.1 Forward current vs. Forward voltage

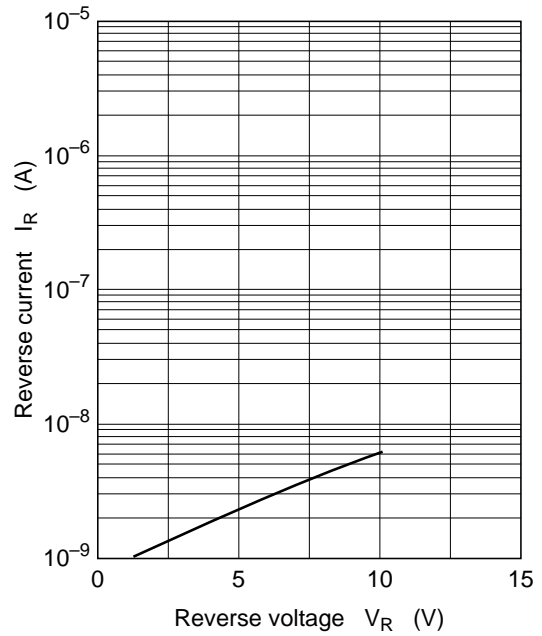


Fig.2 Reverse current vs. Reverse voltage

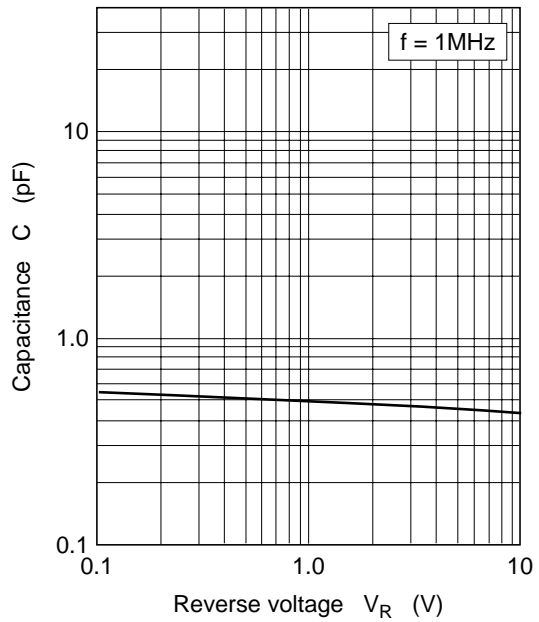
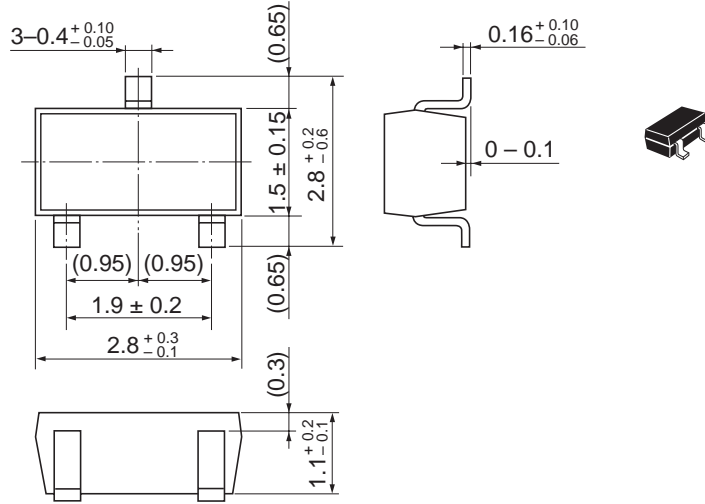


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions

As of January, 2003
Unit: mm



Package Code	MPAK
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.011 g

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